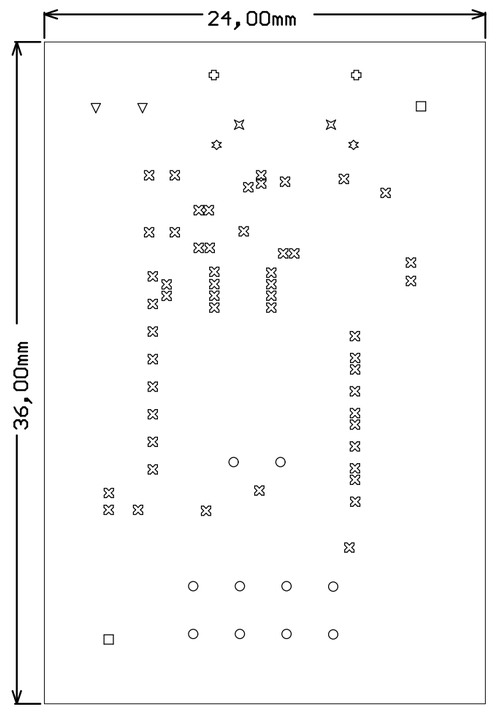
Layer Stackup 4 FR4 TG150			
Top Soldermask	25 um	standard	
Layer1 Top	35 um	Signal / Zdiff 100R	L 125um / S 125um / L 125um
Prepreg 2x1080	140 um		
Layer2	35 um	Plane / Ref.	
Core / Prepreg	1200 um		
Layer3	35 um	Plane / Ref.	
Prepreg 2x1080	140 um		
Layer4 Bottom	35 um	Signal / Zdiff 100R	L 125um / S 125um / L 125um
Bottom Soldermask	25 um	standard	
Thickness approx.	1600 um		



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type	Drill Layer Pair
⊠	53	0,200mm (7,87mil)	PTH	Round	Layer1 Top - Layer4 Bottom
✪	2	0,550mm (21,65mil)	PTH	Slot	Layer1 Top - Layer4 Bottom
⊠	2	0,800mm (31,50mil)	NPTH	Round	Layer1 Top - Layer4 Bottom
✪	2	0,850mm (33,47mil)	PTH	Slot	Layer1 Top - Layer4 Bottom
▽	2	0,900mm (35,43mil)	PTH	Round	Layer1 Top - Layer4 Bottom
○	10	1,000mm (39,37mil)	PTH	Round	Layer1 Top - Layer4 Bottom
□	2	2,600mm (102,36mil)	PTH	Round	Layer1 Top - Layer4 Bottom
	73 Total				

Slot definitions : **Routed Path Length** = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

All drills (PTH and NPTH) should run in one work process

Title: CSI2-RPI-NANO_Rev01	Allied Vision Technologies Taschenweg 2a Germany Stadtroda		Bare Board Revision: 01
Project: CSI2-RPI-NANO	PCB Designer: MTH	Layer Name: Drill Drawing	Bare Board Number:
Date: 27.11.2019	File Name: CSI2-RPI-NANO_Rev01.PcbDoc	SCALE: 1.00	